



S/N 09/854539

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Intel Corporation	Examiner:	Ginette Peralta
Serial No.:	09/854539	Group Art Unit:	2814
Filed:	May 14, 2001	Docket:	884.415US1
Title:	POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN MICROELECTRONIC CIRCUIT PACKAGING		
Assignee:	Intel Corporation	Customer No:	21186

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**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicants state that certain of the items of information contained in the Information Disclosure Statement were first cited in a communication from a foreign patent office in a counterpart foreign application. A copy of the relevant International Search Report, in PCT/US02/25089, mailed August 26, 2003, is also enclosed.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Serial No : 09/854539

Filing Date: May 14, 2001

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Assignee: Intel Corporation

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Dkt: 884.415US1 (INTEL)

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

INTEL CORPORATION

By their Representatives,

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Date Feb. 18, 2004

By Ann M. McCrackin

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 18 day of February, 2004.

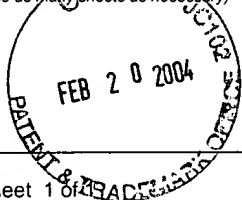
KACIA LEE  
Name

Kacia Lee  
Signature

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

**Applicant Number** 09/854539

**Filing Date** May 14, 2001

**First Named Inventor** Intel Corporation, .

**Group Art Unit** 2814

**Examiner Name** Peralta, Ginette

Sheet 1 of 1

**Attorney Docket No:** 884.415US1

**US PATENT DOCUMENTS**

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-2001/0013654-A1	08/16/2001	Kalidas, N., et al.	257	738	12/22/1999
	US-2002/0008314-A1	01/24/2002	Takeuchi, Y.	257	697	04/13/2000
	US-5,105,257	04/14/1992	Michii, K.	357	70	02/04/1991
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	US-6,130,478	10/10/2000	Dumoulin, A., et al.	257	728	04/18/1998
	US-6,222,246	04/24/2001	Mak, T. M., et al.	257	532	01/08/1999
	US-6,239,482	05/29/2001	Fillion, Raymond A., et al.	257	678	06/21/1999
	US-6,388,333	05/14/2002	Taniguchi, F., et al.	257	777	06/27/2000
	US-6,590,291	07/08/2003	Akagawa, M.	257	774	01/25/2001

**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T <sup>2</sup>
	EP-0149317	07/24/1985	Heeks, J. S., et al.	H05K	3/28	
	EP-0361825	04/04/1990	Misawa, H.	H01L	23/522	
	EP-0431205	06/12/1991	Schroeder, J. A.	H01L	23/498	
	JP-10-125721	05/15/1998	Chikako, H.	H01L	21/60	
	JP-11-204688	07/30/1999	Kenji, A.	H01L	23/12	
	JP-2000-243870	09/08/2000	Akira, K.	H01L	23/12	
	JP-2000-307005	11/02/2000	Yasushi, T.	H01L	21/82	

**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		CHEN, CHANG-LEE, et al., "Bond Wireless Multichip Packaging Technology for High-Speed Circuits", <u>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</u> , 15, NY, US, (1992), 451-456	
		DAUM, W., et al., "Overlay High-Density Interconnect: A Chips-First Multichip Module Technology", <u>IEEE Computer Society</u> , 26, Long Beach, CA, US, (1993), 23-29	
		GDULA, MICHAEL, et al., "An Overlay Interconnect Technology for 1GHz. and Above MCMs", <u>Proceedings of the Multi Chip Module Conference (MCMC)</u> , Santa Cruz, US, (1992), 171-174	

**EXAMINER**

**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached